

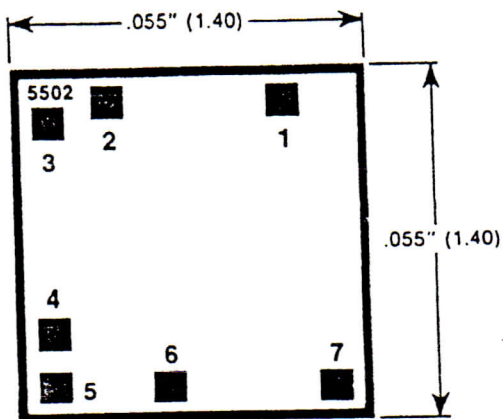


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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



- 1. NULL
- 2. INVERTING INPUT
- 3. NONINVERTING INPUT
- 4. V-
- 5. NULL
- 6. OUTPUT
- 7. V+

Top Material: Aluminum
Backside Material: Silicon
Bond Pad Size: .004" X .004" min.
Backside Potential:
Mask Ref: MTLF 930 Rev.A

APPROVED BY: DK

DIE SIZE .055 x .055"

DATE: 6/22/16

MFG: Micro Power

TICKNESS .015"

P/N: OP02